Fig. 4 shows the end phase of applying into the protective layer 5. The wafer 4 is returned completely to its flat shape and rests in the protective layer 5 parallel to the assembly carrier 6. The negative pressure in the flow apertures to hold the wafer 4 is removed, the wafer 4 detaches itself from the carrying body 2, which then travels back. The wafer 4 could also be secured to the assembly carrier 6 in an electrostatic manner.

Please cancel Claims 1 and 4 in their entirety.

In the Claims, substitute the following Claims 2, 3 and 5-12 (Amended) for the pending Claims 2, 3 and 5-12.

2. (Amended) The method according to claim 10, wherein when laid the substrate (4) applies a constant pressure on the protective layer (5).

3. (Amended) The method according to claim 2, wherein a pressure medium is applied to a side of the substrate (4) remote from the protective layer (5).

5. (Amended) The method according to claim 3, wherein a carrying body (2) moveable relative to the assembly carrier (6) and a portion (8) facing the protective layer (5) carries the substrate (4) and has a plurality of flow apertures (3, 7) for accommodating the pressure medium.

6. (Amended) The method according to claim 5, wherein the portion (8) is planar and the flow apertures (3, 7) are centrally formed ducts and circumferential grooves.

7. (Amended) The method according to claim 6, wherein the ducts (7) are configured as overpressure lines and the grooves (3) are configured as negative pressure lines.

8. (Amended) The method according to claim 7, wherein the portion (8) is one of circular, oval and polygonal in cross-section when viewed from above.

9. (Amended) The method according to claim 10, wherein a pressure medium is applied to a side of the substrate (4) remote from the protective layer (5).

10. (Amended) A method for applying a thin-walled, flat substrate to an assembly carrier (6) with a protective layer (5), the improvement comprising:

with respect to the protective layer (5), arranging the substrate at a spacing and curved in a convex manner, contacting the protective layer (5) with the substrate (4), and laying the substrate (4) over the protective layer (5) from a contact point towards an edge of the substrate, and the substrate being arched and detached from a carrying body (2) by controlling a pressure of a medium in a cavity between the substrate (4) and the carrying body (2).

11. (Amended) The method according to claim 5, wherein the flow apertures (3, 7) are centrally formed ducts and circumferential grooves and the ducts (7) are configured as overpressure lines and the grooves (3) are configured as negative pressure lines.

12. (Amended) The method according to claim 5, wherein the portion (8) is one of circular, oval and polygonal in cross-section when viewed from above.